

Electronic Patent Application Fee Transmittal

Application Number:	10611334
Filing Date:	30-Jun-2003
Title of Invention:	MEMS packaging using a non-silicon substrate for encapsulation and interconnection
First Named Inventor/Applicant Name:	John Heck
Filer:	Kevin Reif/cathy dikes
Attorney Docket Number:	42P16325

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Independent claims in excess of 3	1201	2	200	400
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Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				400